

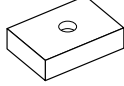
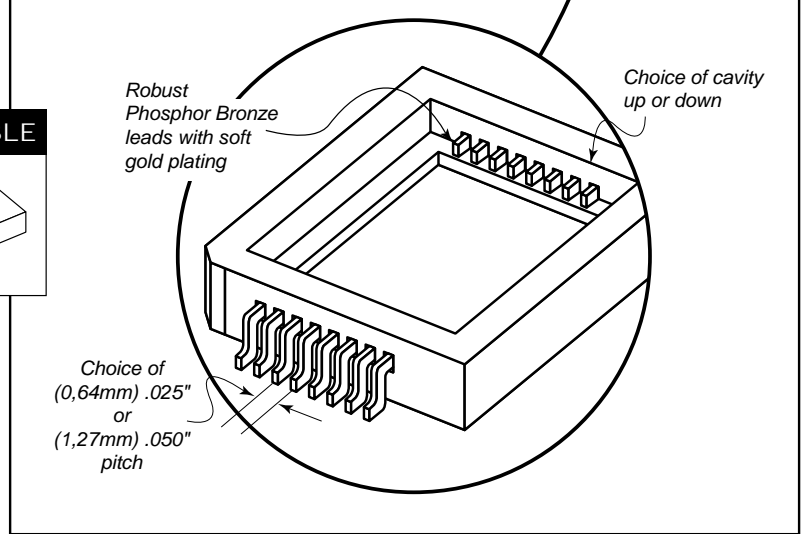
CHIP PACKAGE CPC2 SERIES

SPECIFICATIONS

Materials:
Insulator Material: Liquid Crystal Polymer
Contact Material: Phosphor Bronze
Operating Temp Range: -65°C to +105°C with Tin; -65°C to +125°C with Gold Plating:
 Au over 50µ" (1,27µm) Ni
Current Rating: Testing Now!
Max Processing Temp: 230°C for 60 seconds
SMT Lead Coplanarity: (0,10mm) .004" max

ALSO AVAILABLE

Optional lids for chip/wire bond protection.

CPC2 - 1 NO. OF POSITIONS - LEAD PITCH - BODY STYLE - PLATING OPTION - OTHER OPTION

04, 08, 10, 16, 20, 24, 28

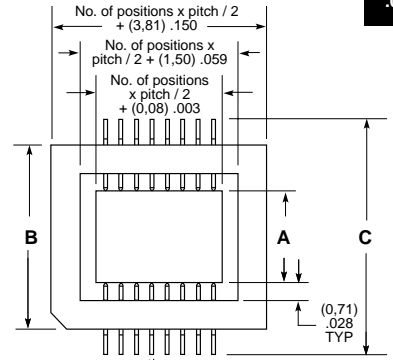
-B = (0,64mm) .025" Pitch
 -E = (1,27mm) .050" Pitch

Specify BODY STYLE from chart

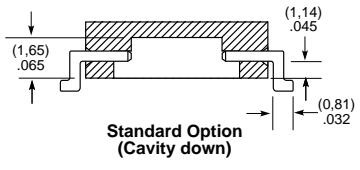
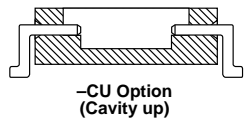
-SG = 30µ" (0,76µm) Soft Gold (.9999 pure)

Leave blank for Cavity Down
 -CU = Cavity Up
 -LDC = (1,52mm) .060" thick cupped lid with (0,76mm) .030" cavity
 -LDF = (0,76mm) .030" thick flat lid

BODY STYLE	A	B	C
-01	(3,81) .150	(7,54) .297	(9,68) .381
-02	(7,62) .300	(11,35) .447	(13,49) .531
-03	(12,70) .500	(16,43) .647	(18,57) .731



LEAD PITCH	D
-B	(0,64) .025
-E	(1,27) .050



Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.